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一级代理商：

深圳市 电子有限公司

地址 区西乡大道302号金源商务大厦B座三楼

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1. Feat res

(1) C rren ran fer ra io(CTR : MIN. 50% a IF = 5mA, VCE = 5V, Ta=25)

(2) High inp -o p i ola ion ol age （VISO=3,750Vrm ）

(3) High collec or-emi er ol age （VCEO = 80V）

(4) SOP-4 package

(5) Opera ing Tempera re -55 o 125

(6) ESD pa HBM 8000V/MM 2000V

(7) Safe appro al

UL appro ed(No.E323844)

VDE appro ed(No.40029733)

CQC appro ed (No.CQC19001231256)

(8) In compliance i h RoHS, REACH andard

(9) MSL Cla Ⅰ

2. Instr ctions

- -357-( ) , .

  4 .

- -357-( ) 2.54

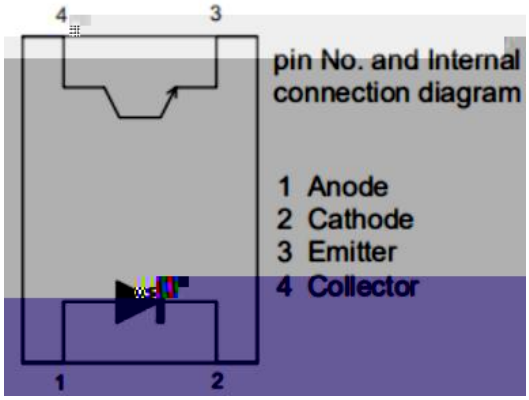
3. Application Range

(1) .

(2)

(3) ,

4. Functional Diagram



5. Ma Absol te rated Val e (Normal Temperat re=25℃)

Parameter		S mbol	Rated Val e	Unit
			50	
			125	℃
			6	
			70	
			80	
			7	
			50	
			150	
			200	
*1			3750	
			-55 + 125	
+			-55 + 150	℃
*2			260	

*1. , 1 , = 40 60%
:

(1) .
(2) .
(3) .

*2. 10 .

6. Opto-electronic Characteristics

Parameter		S mbol	Min	T p.*	Ma	Unit	Condition
			---	1.2	1.4		=20
			---	---	5		=5
			---	30	250		=0, =1
			---	---	100		=20 , =0
			80	---	---		=0.1 =0
			7	---	---		=0.1 =0
	*1.		50	---	600	%	=5 =5
			2.5	---	30		
		( )	---	---	0.2		=20 = 1
			5 10^{10}	1 10^{11}	---		500 40 60% . .
			---	0.6	1		=0, =1
			---	2.9	10		=2 , =2 , =100
	+		---	4.5	10		

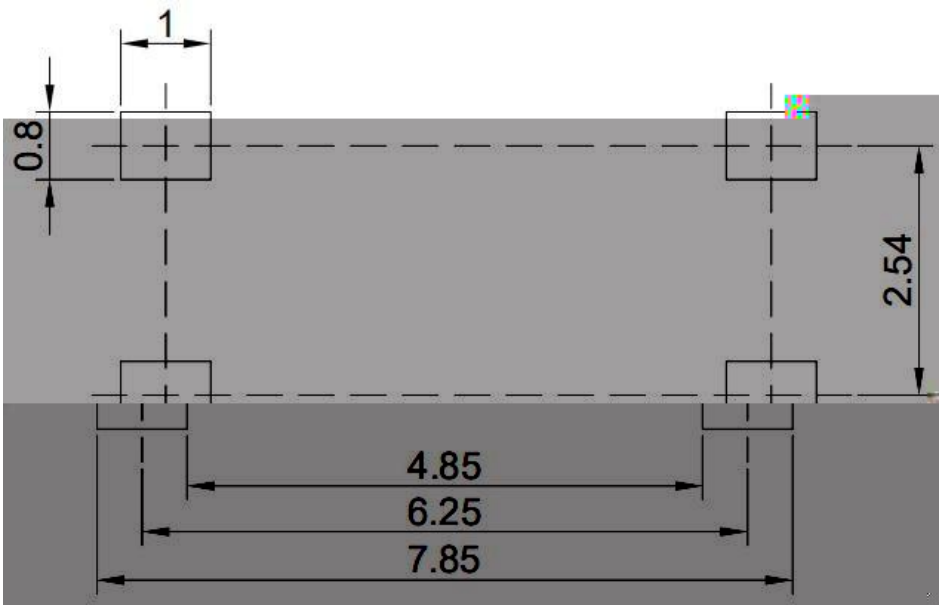
- = / 100%

9. Naming R le

1. Man fac rer : OI
2. Par N mber : 35
3. Rank Code
4. Year Code 020' and o on.
5. Week Code 01 mean he fir eek, 02 mean he econd eek and o on.
6. . VDE Code

10. O ter Dimension

11. Recommended Foot Print Patterns (Mo nt Pad)



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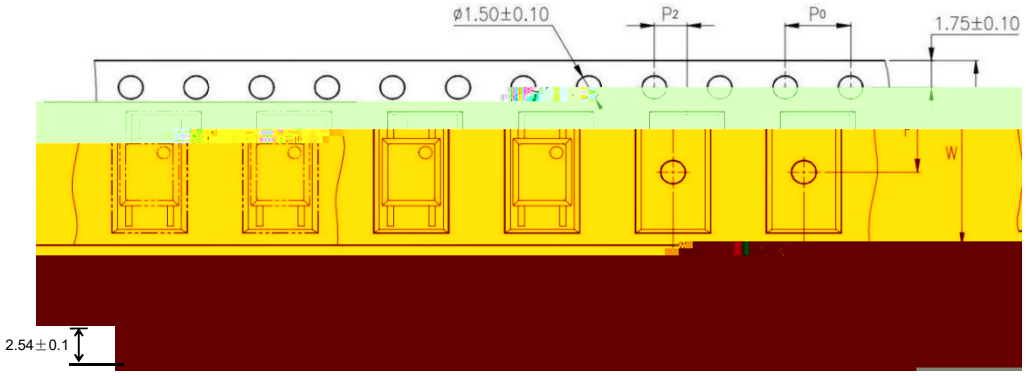
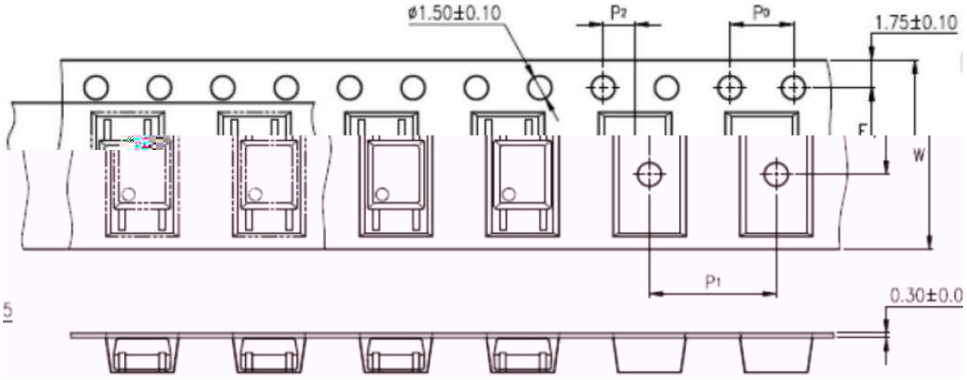
12. Taping Dimensions

（1）OR-357-TP



（2）OR-357-TP1



Description	S mbol	Dimension in mm(inch)
		12 0.3（0.472）
	0	4 0.1（0.157）
		5.5 0.1（0.217）
+	2	2 0.1（0.079）
+	1	8 0.1（0.315）

Package T pe	TP/TP1
( )	3000

14. Reliabilit Test

NO.	ITEMS	Reliabili Te ing				
		QTY. (Pcs)	Condition	Process	Device	Standard
1	RSH 耐焊接热	22	260±5℃	10 /3 次	锡炉	JESD22-A106
2	HTSL 高温存储	77	125℃	168 hr 500 hr 1000 hr	高温烤箱 测试仪	JESD22-A103
3	LTSL 低温存储	77	-55℃	168 hr 500 hr 1000 hr	低温箱 测试仪	JESD22-A119
4	TC 温度循环	77	H:125℃ 15min ∫ 5min L:-55℃ 15min	300 c cle	冷热冲击机	JESD22-A104
5	TS 温度冲击	77	H:100℃ 5min ∫ 15 L:-40℃ 5min	300 c cle	冷热冲击机	JESD22-A106
6	HTOL 高温操作	77	110 C IF=10mA Vce=5V	168 hr 500 hr 1000 hr	高温烤箱 测试仪、老 化电路板	JESD22-A108
7	ESD-HBM 人体模式	22	≥8KV 1C cle	1次	ESD静电测 试仪	JESD22-A114
8	SD 可焊性	22	Pb-free 245±5℃	5S/1次	锡炉	JESD22-B102
9	HTRB 高温反向偏压	77	HTRB @125℃ Vce=80	168 hr 500 hr 1000 hr	高温烤箱 ，测试仪	JESD22-A103
10	H3TRB 温湿度反向偏 压，寿命试验	77	H3TRB 85℃,85%RH Vce=80	168 hr 500 hr 1000 hr	恒温恒湿 机，测试仪	JESD22-A101
11	Autoclave 压力锅	77	Ta=121 ℃,100%RH,2a m	96hr	压力锅	JESD22-A102

15. Temperat re Profile Of Soldering

（1） (- -020 + +)

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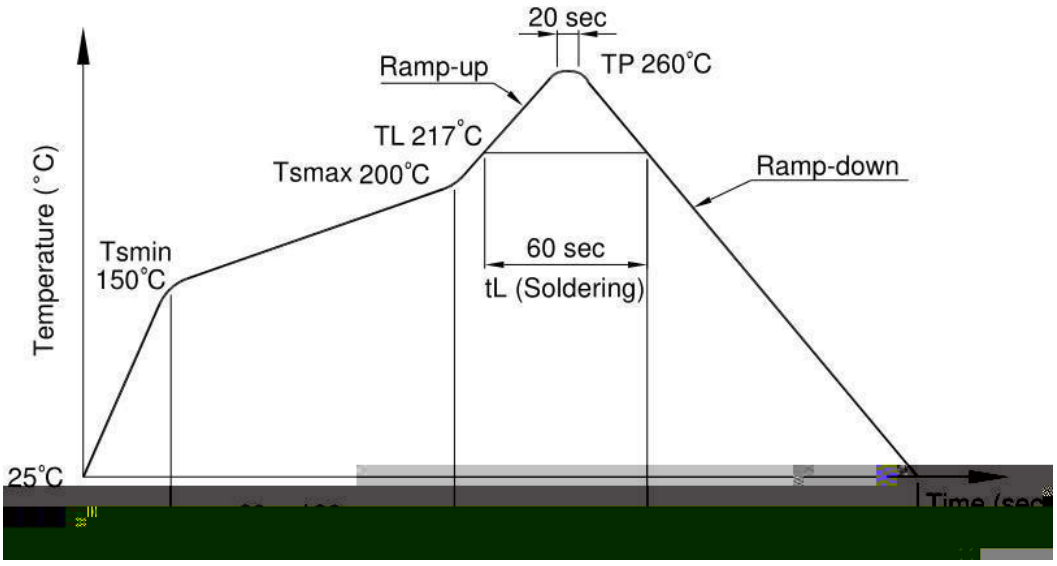
Profile item	Conditions
- ( )	150
- ( )	200
- ( ) ( )	90 30
- ( )	217
- ( )	60
	260
	20
-	3 / .
-	3 6 /
	⩽3



16. Characteristics Curves

Fig.1 Forward current vs Ambient temperature

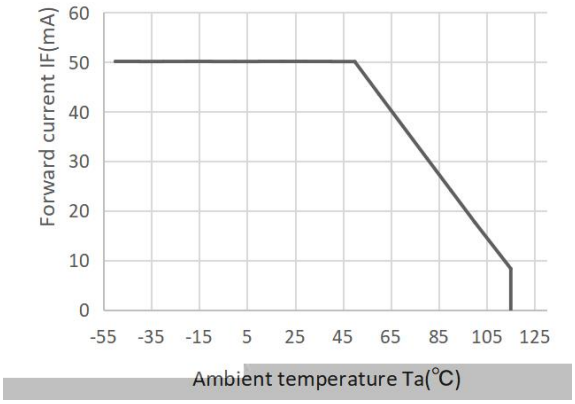


Fig.2 Collector Power Dissipation vs. Ambient temperature

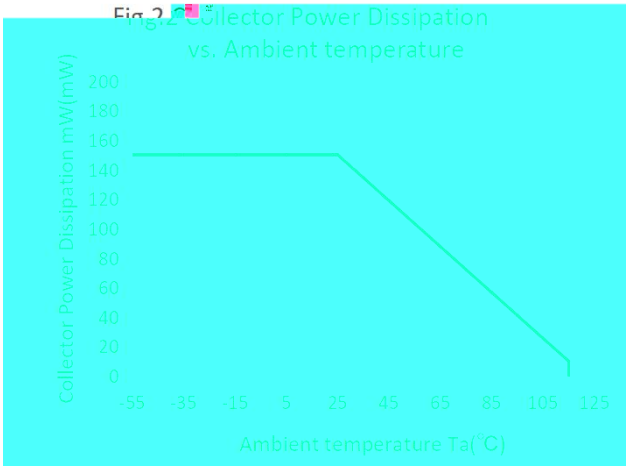


Fig.3 Collector-emitter Saturation Voltage vs. Forward Current

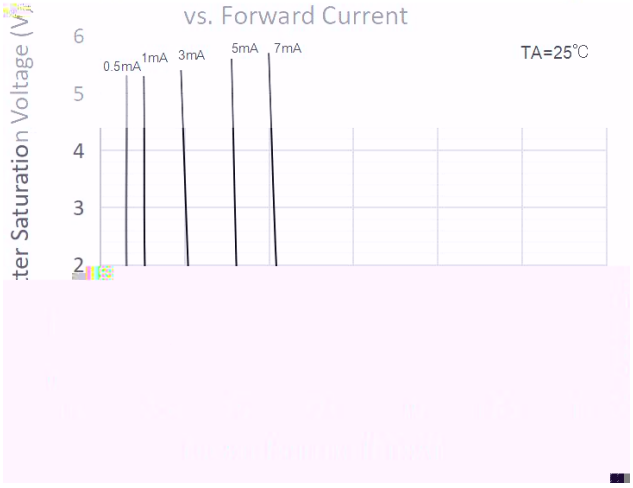


Fig.4 Forward Current vs. Forward Voltage

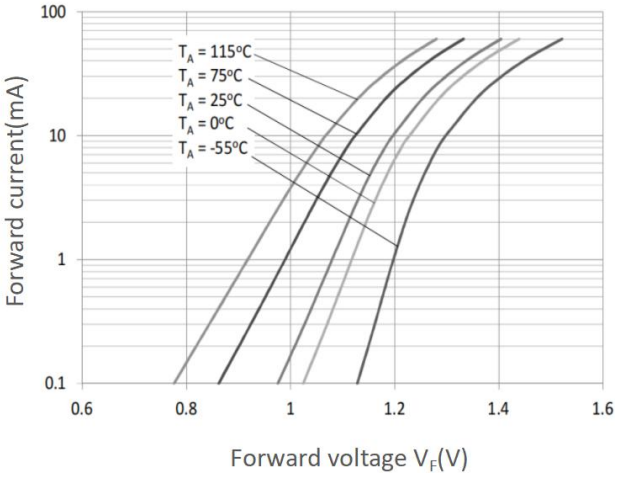


Fig.5 Forward Current vs. Current Transfer Ratio

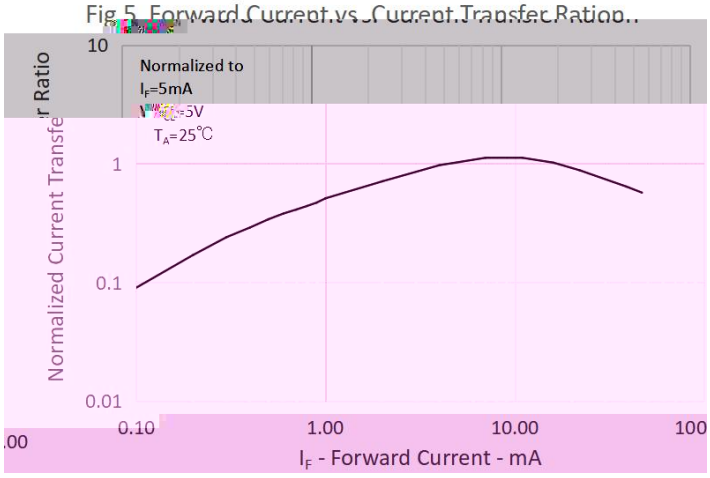


Fig.6 Collector Current vs. Collector-emitter Voltage

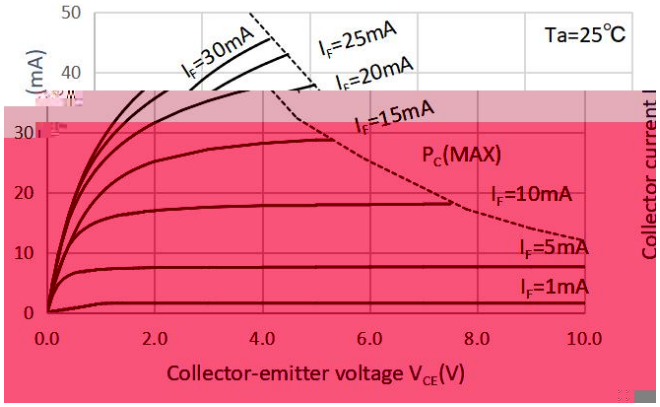


Fig.7 Relative Current Transfer Ratio vs. Ambient Temperature

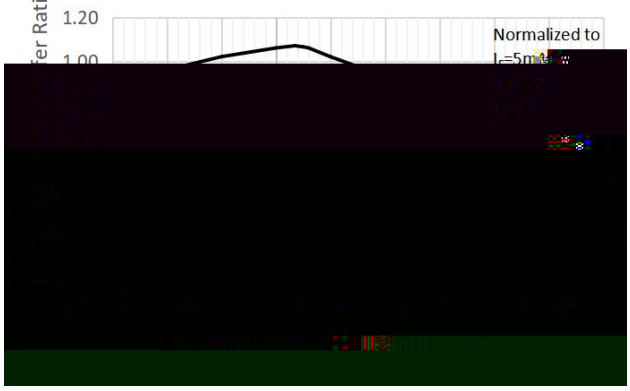


Fig.8 Collector-emitter Saturation Voltage vs. Ambient Temperature

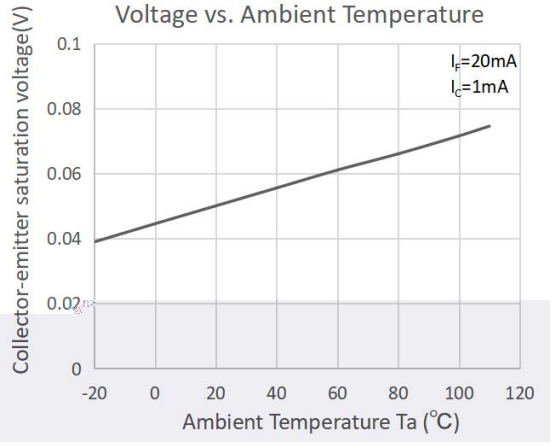


Fig.9 Collector Dark Current vs. Ambient Temperature

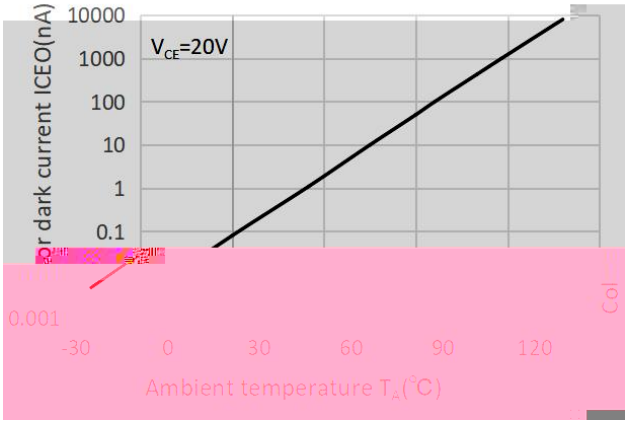


Fig.10 Respinse Time vs. Load Resistance

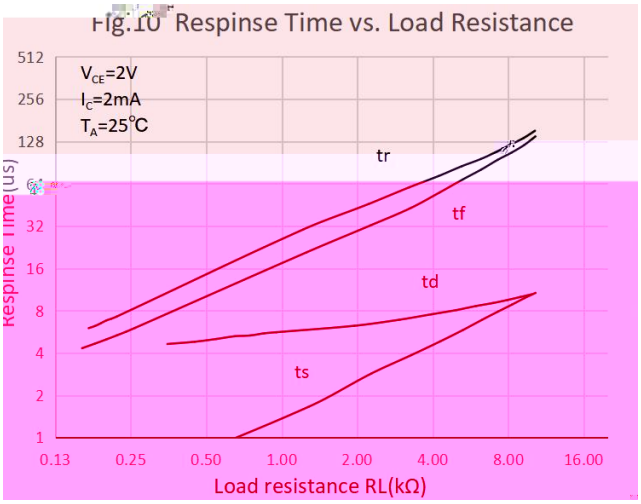
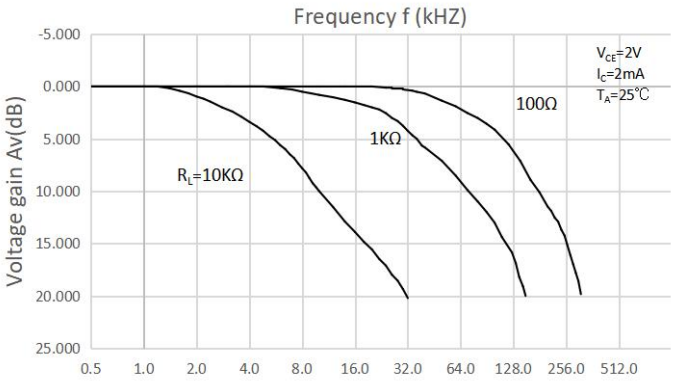
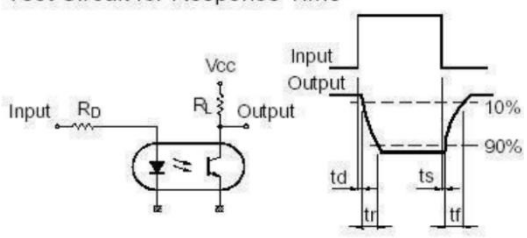


Fig.11 Frequency Response



Test Circuit for Response Time



Test Circuit for Frequency Response